

# iPower3 Conference “Electronic Packaging for Net Zero”

Advanced Propulsion Centre, University of Warwick

Thursday 2nd December 2021

[Register Here](#)



## Highlights

*Enabling Electric Powertrain Technologies by BMW Group*

*Sintering for Power Electronics Assembly*

*Packaging for Fast Switching Die*

*Face to Face Networking with Exhibitors representing materials, modelling, manufacturing, test and failure analysis equipment suppliers*

**Achieving Net Zero** will present some of the most significant challenges to be faced by a wide range of electrical and electronic based industries in the next decade. Getting reliable and fully functional products to market will require electronic and electrical packaging solutions that can operate at higher currents and voltages, faster frequencies and increased temperatures. This conference will hear from OEMs, material and equipment suppliers and academia about the current and future solutions to meet these demanding requirements. Many of the solutions will be applicable to a wider range of different application areas and attendees can learn how other sectors are approaching the challenges and assess if they will be applicable to their own applications.

The Conference will describe the latest advances in **electronic package design, materials, processes, next-level-integration and performance** while maintaining **reliability, sustainability, manufacturability and cost-competitiveness** in **Power Electronics for Generation, Conversion, Distribution and Energy Storage** applications.

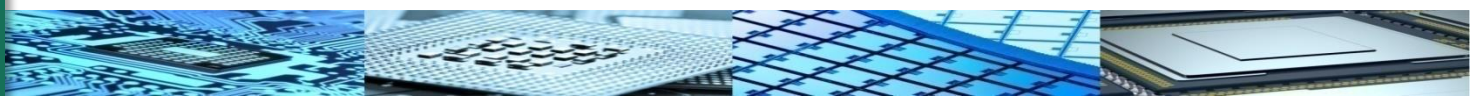
iPower3 aims to provide the **Delegates** with an opportunity to learn from and network with **leading Industry Experts and Exhibitors** as they share their experiences, developments and opportunities.

## Registration Prices

	<i>Delegates</i>
<i>IMAPS Member</i>	<i>85</i>
<i>IMAPS Student</i>	<i>30</i>
<i>Non member</i>	<i>155</i>
<i>Corporate Member Exhibitor</i>	<i>385</i>
<i>Non-Member Exhibitor</i>	<i>585</i>

*Prices - £ exclude VAT*

**“Where Industry Meets”**



IMAPS-UK Technical Conference

## Conference Agenda:

**09:00 Registration and Networking**

**09:30 Welcome, Introduction to IMAPS-UK and Our Sponsor - Inseto (UK) Ltd**

**09:40 Overview of Advanced Propulsion Centre (APC)**

**09:50 Session One:**

- **Keynote: @FutureBEV Enabling Powertrain Technologies for BEV, David Bock, BMW Group**
- **GaNSiC – Direct dispensing of high/low pressure silver sinter materials – John Boston, CIL**

**10:50 Exhibitor Elevator Pitches**

**11:15 Refreshments, Exhibition and Networking**

**11:45 Session Two:**

- **Pre-Packaging of Fast Switching Die – Geoff Haynes, RAM Innovations**
- **Use of High Accuracy Low Force SIP Technology Developments for Power Devices – Simon Broadhurst, K&S**

**12:45 Lunch, Exhibition and Networking**

**13:45 Session Three:**

- **Packaging and Assembly Trends for Next Generation Power Modules – Huub Claassen, Boschman Technologies**
- **Recent Progress on Copper Sintering for High Power Semiconductor Packaging – Yangang Wang, Dynex Semiconductor**

**14:45 Refreshments, Exhibition and Networking**

**15:05 Session Four**

Addressing the Needs for EV Design, New Packaging Solutions and Future Challenges – Nikola Kontic, Zuken UK

- **Immersion Cooled Power Electronics – Marc Brand, Supply Design**
- **Leadframe Design and Trim/Form Solutions – Mark Kenny – Rydon Technology**

**16:30 Close**

IPower3 Conference is sponsored by **Inseto (UK) Ltd**



## Registration for iPower3

**Delegates** will receive a **Conference Booklet** containing details of the **Presentations and Speakers** and details of the **Exhibitors**. The **presentations** will be available to **download from the IMAPS-UK website** after the event.

## Exhibitors at iPower3 Conference

The current Exhibitors are:

- **Accelonix** – specialist equipment sales and support for microelectronics, battery and PCB assembly
- **Alter Technology** – leading provider and micro and optoelectronics services in space and harsh environment markets
- **Boschman** – is a one stop shop for highly innovative packaging solutions
- **Custom Interconnect Ltd** – electronics manufacturing, advanced technologies and design services in power electronics for BEVs/PHEVS
- **Gen 3** – specialist manufacturer and distributor of test and measurement equipment
- **Heraeus Electronics** – Materials for power electronics assembly and packaging
- **Inseto** – manufacturing equipment, assembly materials and adhesives
- **Carl Zeiss** – materials characterisation and failure analysis equipment
- **Zuken** – global software company offering advanced design solutions for electronic systems

### The Venue

**Advanced Propulsion Centre,**

**IIPSI Building,**

**University Road**

**University of Warwick**

**Coventry**

**CV4 7AL**

[www.apcuk.co.uk](http://www.apcuk.co.uk)

The **Advanced Propulsion Centre** is working closely with industry and academia to identify technology-led opportunities to strengthen the UK research to manufacture supply chain capabilities.